

IN THE SPECIFICATION:

After the title, please include the following --

RELATED APPLICATIONS

A1
This application is a continuation of U.S. Application Serial Number 08/944,135, which is a file wrapper continuation of U.S. Application Serial Number 08/618,072, filed February 27, 1996. --

IN THE CLAIMS:

Please cancel claims 2-11 without prejudice.

Please add the following claims:

12. A processor for a spin coating device including a chuck defining a wafer plane, comprising:
at least one dispenser; and
a suction mechanism generally around said at least one dispenser and offset from said wafer plane.
13. The processor in claim 12, wherein said at least one dispenser further comprises:
a first dispenser on a first side of said wafer plane; and
a second dispenser on a second side of said wafer plane.
14. A bead remover for a wafer having an edge, comprising:
a negative pressure mechanism configured to be spaced from said edge; and
a solvent-dispensing mechanism aligned with said negative pressure mechanism.